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(54) **ORGANIC LIGHT EMITTING DISPLAY
DEVICE AND METHOD OF
MANUFACTURING THE SAME**

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(57) **ABSTRACT**

Disclosed are an organic light emitting display device to improve optical efficiency and prevent deterioration in reliability of thin film transistors, and a method of manufacturing the same. The organic light emitting display device includes a mirror wall which is disposed on a substrate such that the mirror wall surrounds a light emitting area of each sub-pixel where a light emitting element is disposed, thus preventing total reflection of light produced in the light emitting element and improving optical efficiency by reflecting light travelling toward a non-emitting area to be directed to the light emitting area.

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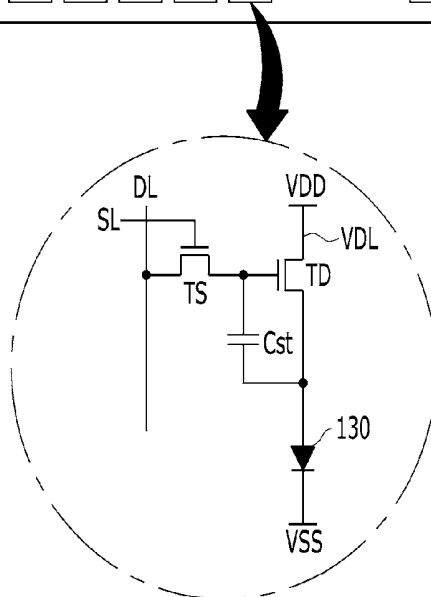
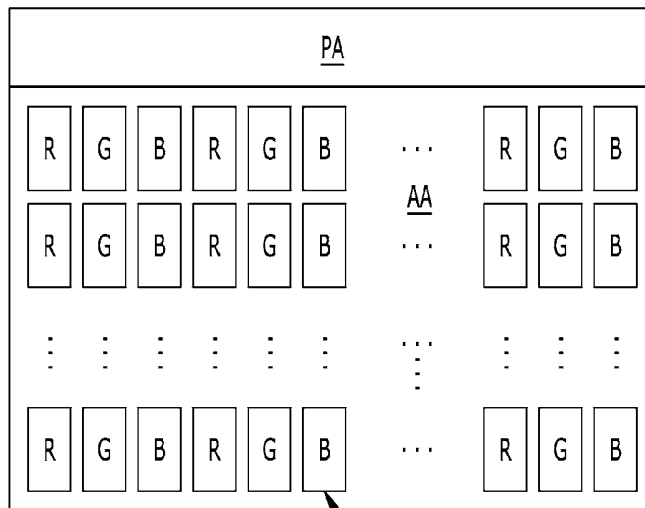


FIG. 1

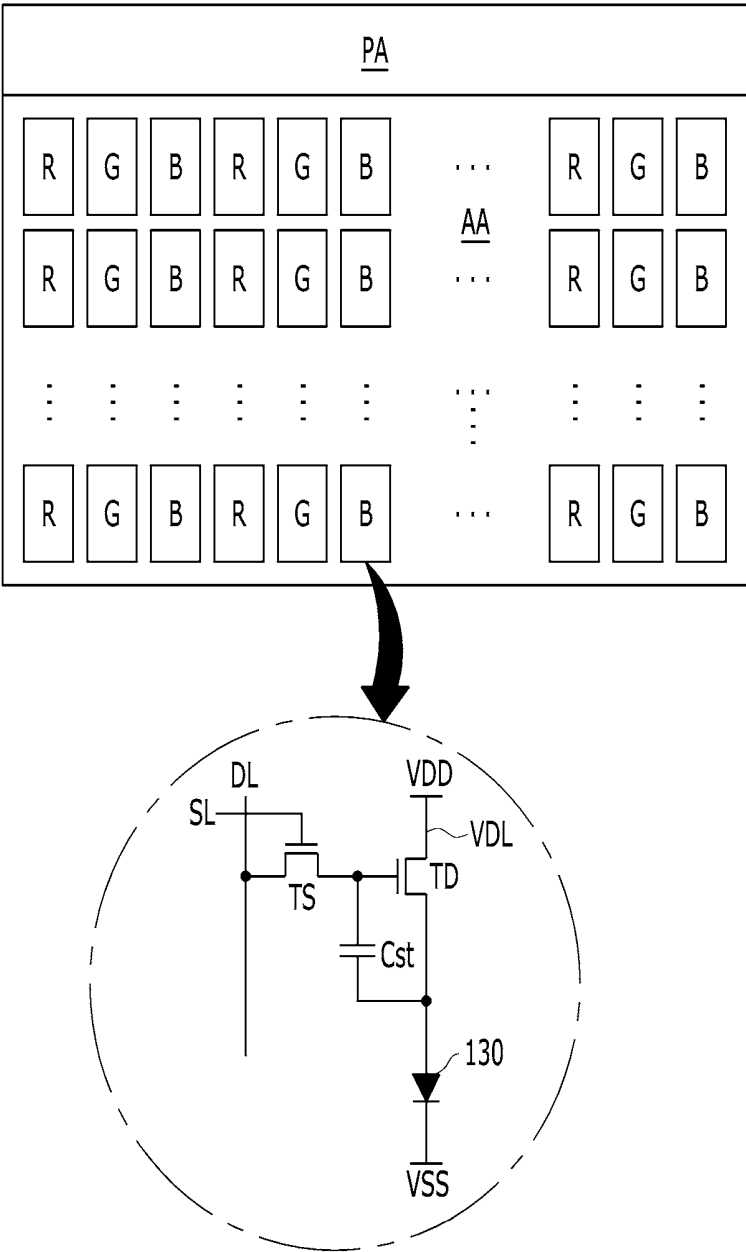


FIG. 2

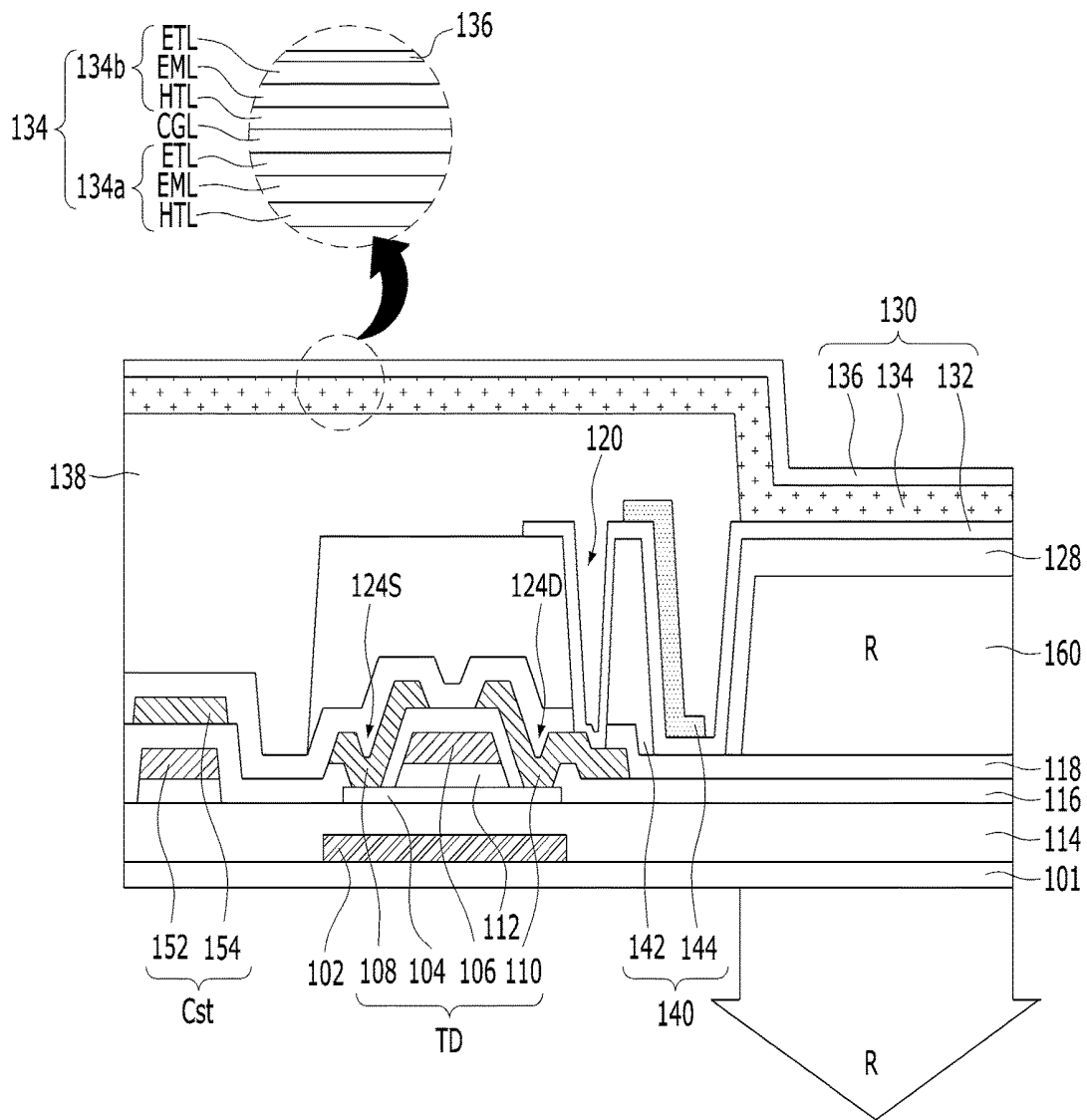


FIG. 3A

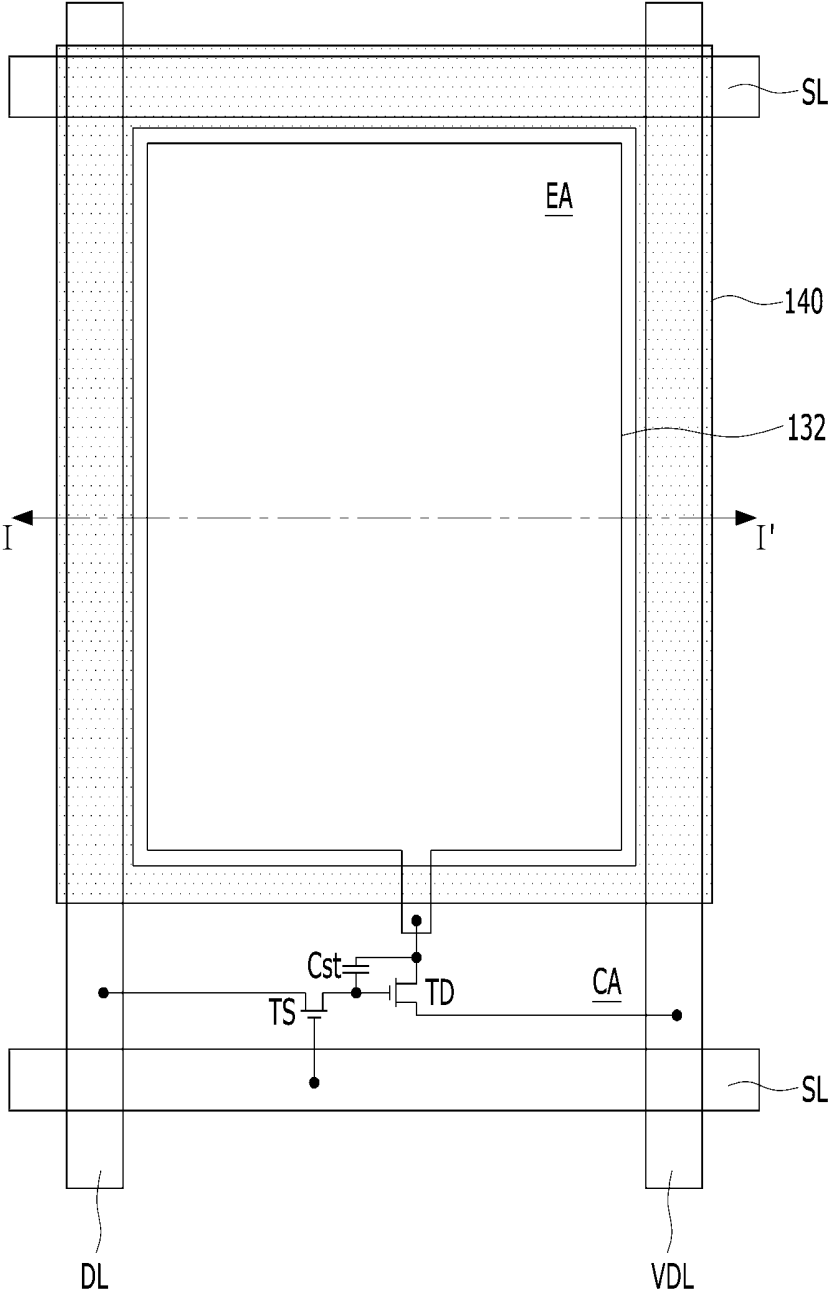


FIG. 3B

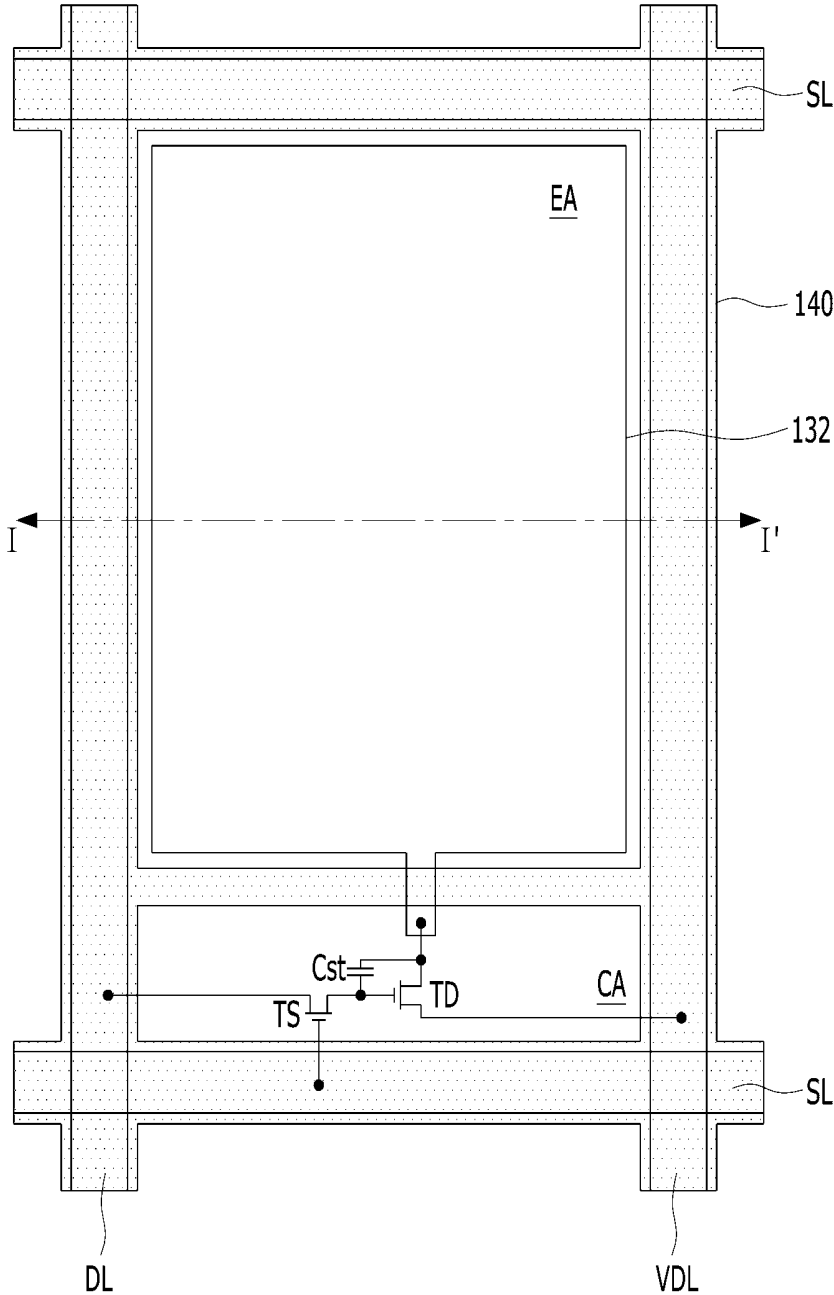


FIG. 4

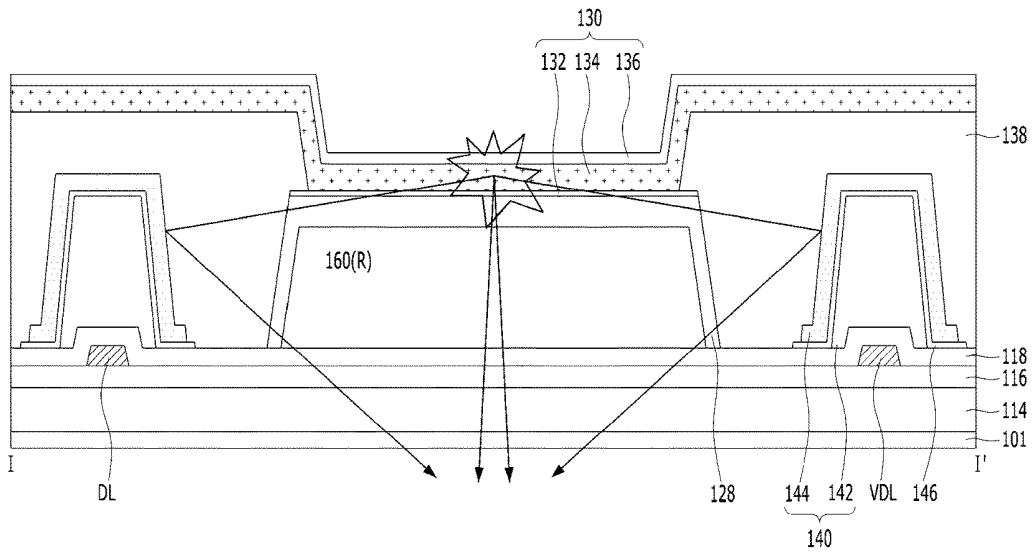


FIG. 5A

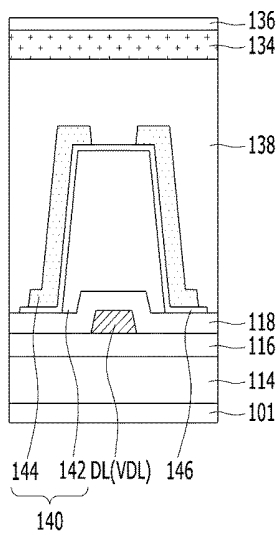


FIG. 5B

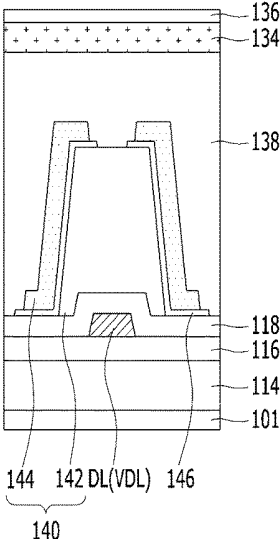


FIG. 6A

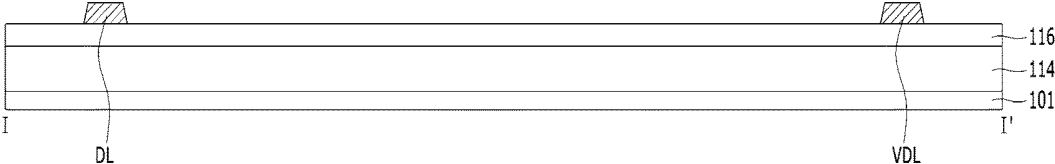


FIG. 6B

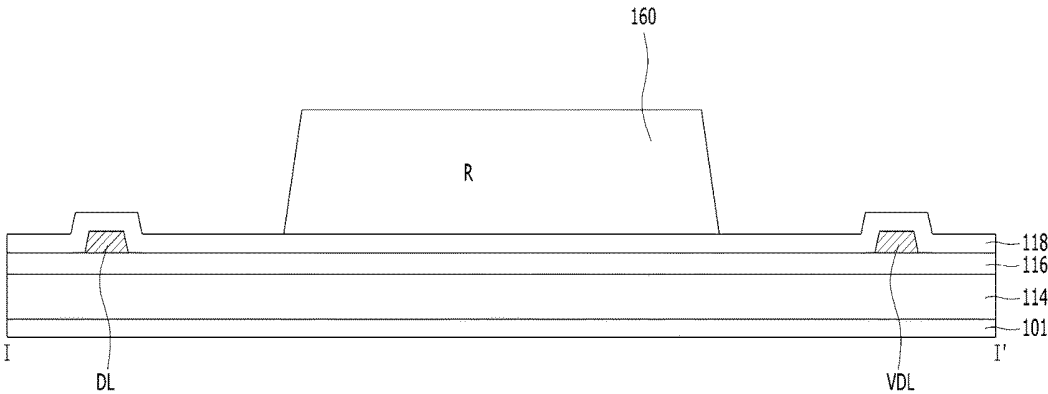


FIG. 6C

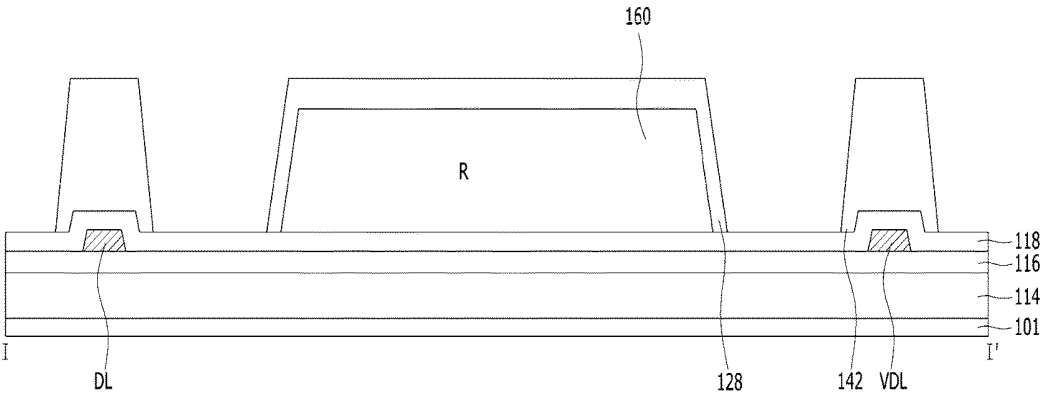


FIG. 6D

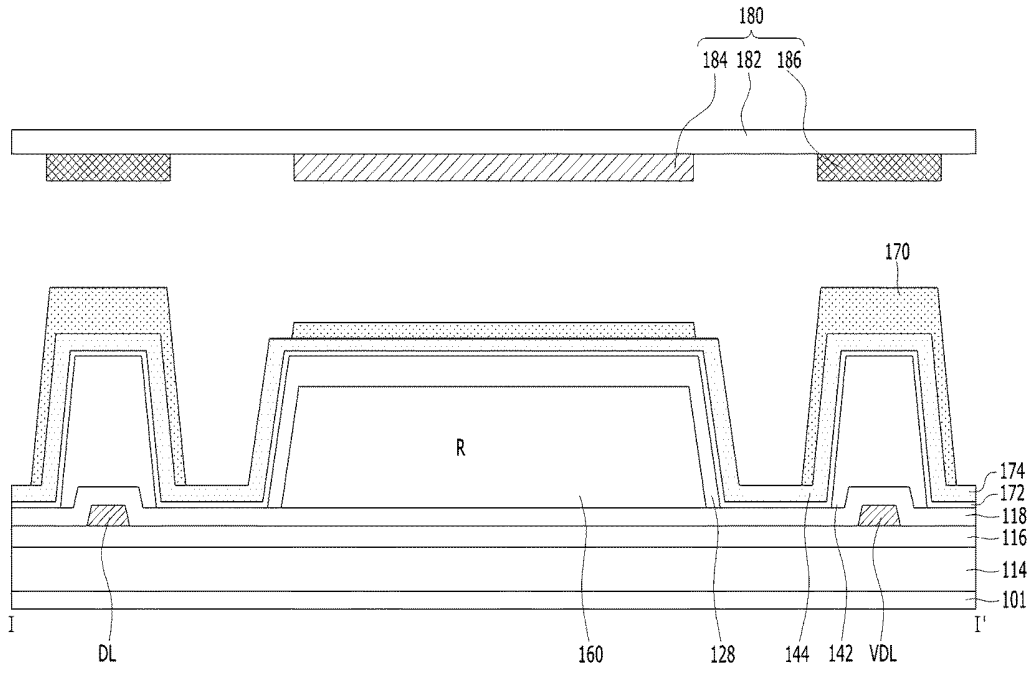


FIG. 6E

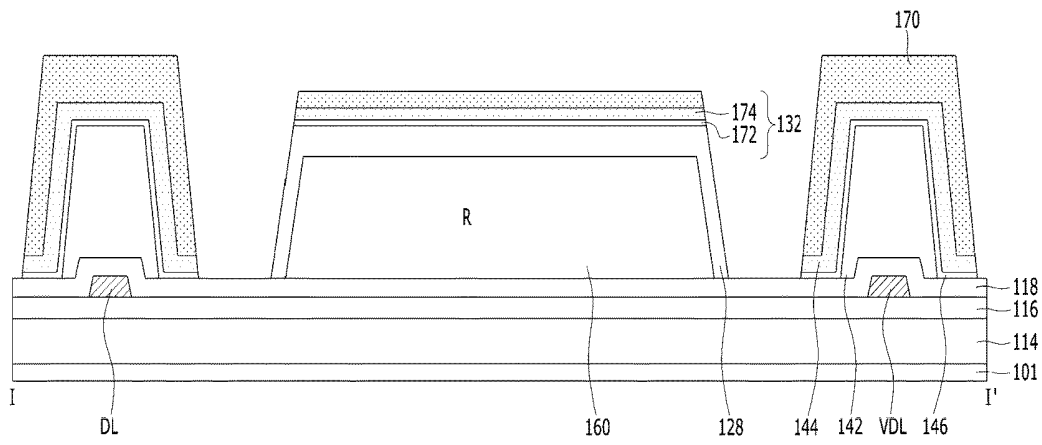


FIG. 6F

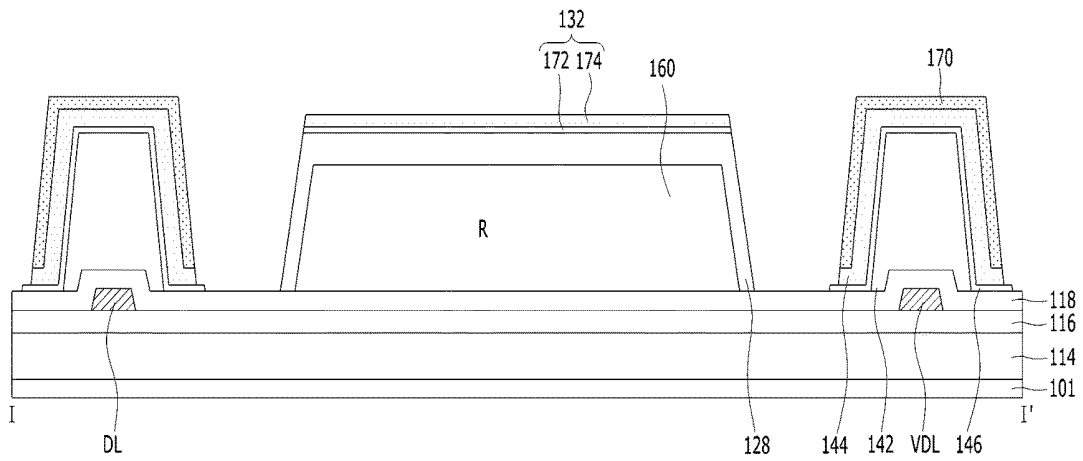


FIG. 6G

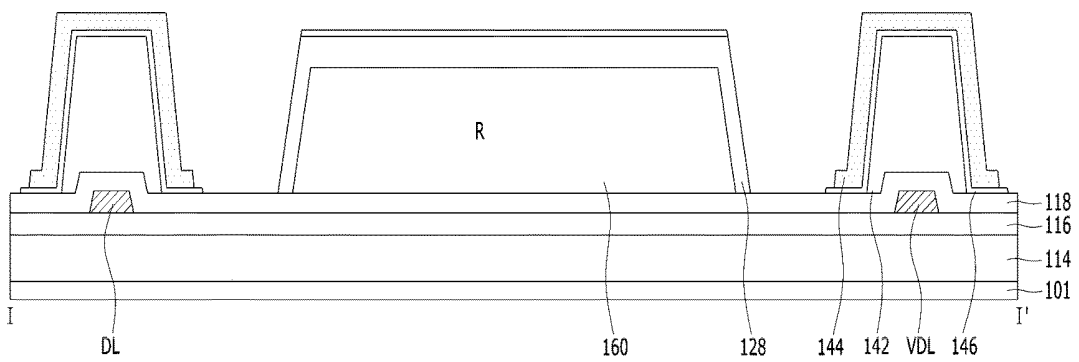


FIG. 6H

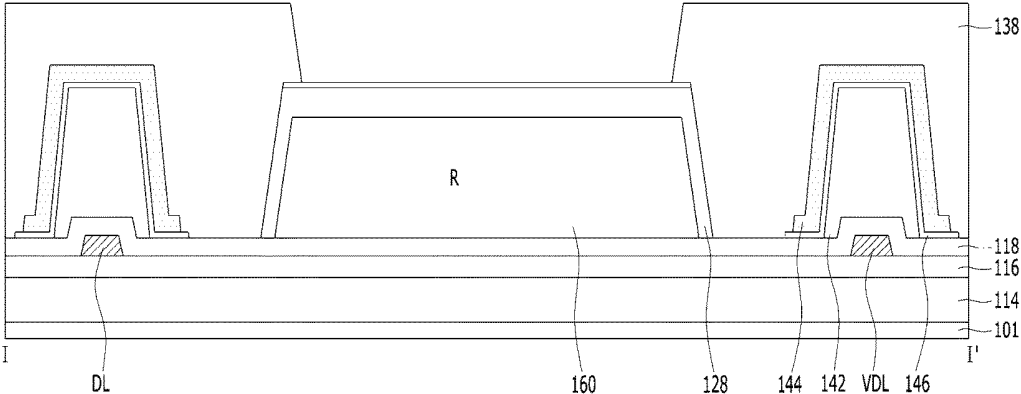
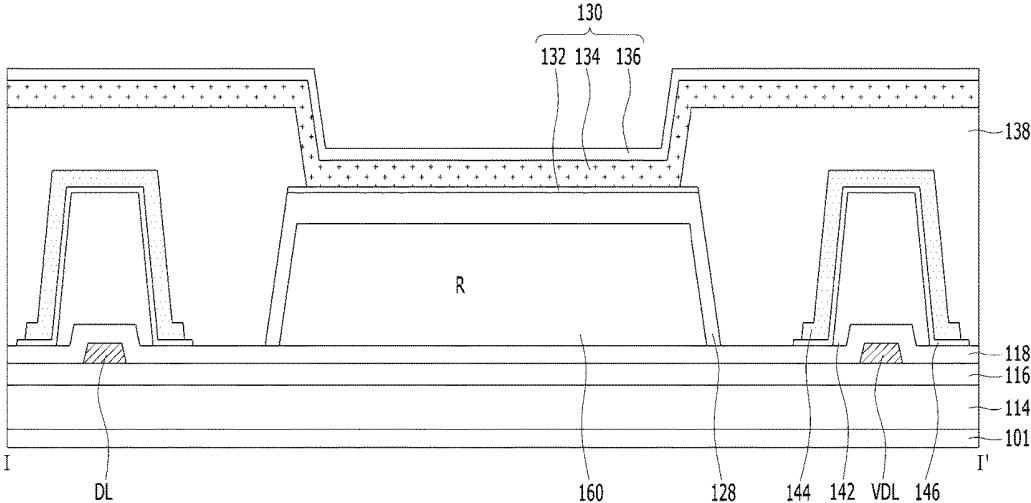


FIG. 6I



**ORGANIC LIGHT EMITTING DISPLAY
DEVICE AND METHOD OF
MANUFACTURING THE SAME**

[0001] This application claims the benefit of Korean Patent Application No. 10-2016-0161945, filed on Nov. 30, 2016, which is hereby incorporated by reference as if fully set forth herein.

BACKGROUND

[0002] Technical Field

[0003] The present disclosure relates to an organic light emitting display device and a method of manufacturing the same. More particularly, the present disclosure relates to an organic light emitting display device to improve optical efficiency and prevent deterioration in reliability of thin film transistors, and a method of manufacturing the same.

[0004] Description of the Related Art

[0005] Image display devices for displaying a variety of information on a screen are significant technologies in the information-technology era and are being developed into slimmer, lighter weight, more portable and higher-functional forms. In response to these requirements, organic light emitting diodes that display an image by controlling the amount of light emitted by an organic light emitting layer attract a great deal of attention as flat panel display devices capable of reducing weight and volume, which are drawbacks of cathode ray tubes. Organic light emitting diodes (OLEDs), which spontaneously emit light, have low power consumption, rapid response speed, high luminous efficacy, high brightness and wide viewing angle.

[0006] Organic light emitting diodes include a light emitting element and a pixel circuit which independently operates the light emitting element and includes a plurality of transistors.

[0007] Here, when light generated in the light emitting element travels toward a substrate, total reflection occurs in an inner area between the light emitting element and the substrate due to the difference in refractive index between thin films disposed between the light emitting element and the substrate. Accordingly, the light extraction efficiency of light emitted to the rear surface of the substrate is lowered to 20 to 35%. In addition, a part of light generated in the light emitting element travels toward a non-light emitting area, rather than a light emitting area, thus causing deterioration in light extraction efficiency. In addition, when light scattered by total reflection which occurs inside the substrate is incident upon the channel of a thin film transistor included in a pixel circuit, it is difficult to control on/off of the thin film transistor due to photon energy, thus disadvantageously causing deterioration in reliability of the thin film transistor.

BRIEF SUMMARY

[0008] Accordingly, the present disclosure is directed to an organic light emitting display device and a method of manufacturing the same that substantially obviate one or more problems due to limitations and disadvantages of the related art.

[0009] In various embodiments, the present disclosure provides an organic light emitting display device having improved optical efficiency and that prevents or reduces deterioration in reliability of thin film transistors, and a method of manufacturing the same.

[0010] Additional advantages, objects, and features of the disclosure will be set forth in part in the description which follows and in part will become apparent to those having ordinary skill in the art upon examination of the following or may be learned from practice of the disclosure. The objectives and other advantages of the disclosure may be realized and attained by the structure particularly pointed out in the written description and claims hereof as well as the appended drawings.

[0011] To achieve these objects and other advantages and in accordance with the purpose of the disclosure, as embodied and broadly described herein, provided are an organic light emitting display device which includes a mirror wall which is disposed on a substrate such that the mirror wall surrounds a light emitting area of each sub-pixel where a light emitting element is disposed, thus preventing total reflection of light produced in the light emitting element and improving optical efficiency by collecting light travelling toward a non-emitting area to the light emitting area, and a method of manufacturing the same.

[0012] In one embodiment, the present disclosure provides an organic light emitting display device that includes a substrate, a plurality of sub-pixels on the substrate, and a reflective barrier. Each of the sub-pixels includes a light emitting element disposed in a light emitting area, and a pixel circuit disposed in a circuit area and configured to operate the light emitting element. The reflective barrier is disposed overlying the substrate and surrounding a perimeter of the light emitting area of each sub-pixel.

[0013] In another embodiment, the present disclosure provides a method of manufacturing an organic light emitting display device that includes: forming a pixel circuit in a pixel area of a sub-pixel on a substrate; forming a light emitting element in a light emitting area of the sub-pixel; and forming a reflective barrier on the substrate, the reflective barrier surrounding a perimeter of the light emitting area.

[0014] It is to be understood that both the foregoing general description and the following detailed description of the present disclosure are exemplary and explanatory and are intended to provide further explanation of the disclosure as claimed.

BRIEF DESCRIPTION OF THE SEVERAL
VIEWS OF THE DRAWINGS

[0015] The accompanying drawings, which are included to provide a further understanding of the disclosure and are incorporated in and constitute a part of this application, illustrate embodiment(s) of the disclosure and together with the description serve to explain the principle of the disclosure. In the drawings:

[0016] FIG. 1 is a plan view illustrating an organic light emitting display device according to the present disclosure;

[0017] FIG. 2 is a sectional view illustrating a sub-pixel of the organic light emitting display device shown in FIG. 1;

[0018] FIGS. 3A and 3B are plan views illustrating embodiments of a sub-pixel of the organic light emitting display device shown in FIG. 2;

[0019] FIG. 4 is a sectional view taken along line "I-I", of the organic light emitting display device shown in FIGS. 3A and 3B;

[0020] FIGS. 5A and 5B are sectional views illustrating various embodiments of a mirror wall shown in FIG. 4; and

[0021] FIGS. 6A to 6I are sectional views illustrating a method of manufacturing the organic light emitting display device shown in FIG. 4.

DETAILED DESCRIPTION

[0022] Reference will now be made in detail to the preferred embodiments of the present disclosure, examples of which are illustrated in the accompanying drawings.

[0023] FIG. 1 is a plan view illustrating an organic light emitting display device according to the present disclosure.

[0024] The organic light emitting display device shown in FIG. 1 includes an active area AA and a pad area PA.

[0025] In the pad area PA, a plurality of pads, which each supply a driving signal to a scan line SL, a data line DL, a high-voltage VDD supply line VDL and a low-voltage VSS supply line disposed in the active area AA, are formed.

[0026] The active area AA displays an image through a unit pixel including a light emitting element 130. The unit pixel includes red R, green G and blue B sub-pixels, or red R, green G, blue B and white W sub-pixels. Each of the sub-pixels includes a light emitting element 130 and a pixel driving circuit independently operating the light emitting element.

[0027] The pixel driving circuit includes a switching transistor TS, a driving transistor TD and a storage capacitor Cst.

[0028] When a scan pulse is supplied to the scan line SL, the switching transistor TS is turned on and supplies a data signal supplied to the data line DL to the storage capacitor Cst and a gate electrode of the driving transistor TD.

[0029] In response to the data signal supplied to the gate electrode of the driving transistor TD, the driving transistor TD controls a current I supplied from the high-voltage VDD supply line VDL to the light emitting element 130, thereby regulating the amount of light emitted by the light emitting element 130. In addition, although the switching transistor TS is turned off, the voltage charged in the storage capacitor Cst enables the driving transistor TD to supply a constant current I until the data signal of the next frame is supplied, thereby allowing the light emitting element 130 to continuously emit light.

[0030] For this purpose, the driving transistor TD includes a gate electrode 106, a source electrode 108, a drain electrode 110 and an active layer 104, as shown in FIG. 2.

[0031] The gate electrode 106 is formed on the gate insulation film 112 which is the same pattern as the gate electrode 106. The gate electrode 106 overlaps a channel region of the active layer 104 such that the gate insulation film 112 is interposed therebetween. The gate electrode 106 is formed as a single layer or multiple layers using any one of Mo, Ti, Cu, AlNd, Al and Cr, or an alloy thereof, but the present disclosure is not limited thereto. For example, the gate electrode 106 may have a multilayer stack structure of Cu/MoTi.

[0032] The source electrode 108 is connected to the active layer 104 exposed through a source contact hole 124S penetrating the interlayer insulation film 116. The drain electrode 110 is connected to the active layer 104 through a drain contact hole 124D penetrating the interlayer insulation film 116. In addition, the drain electrode 110 is exposed through a pixel contact hole 120 penetrating a protective film 118 and a planarization layer 128 and is connected to the anode 132.

[0033] The source electrode 108 and the drain electrode 110 are, for example, formed as a single layer or multiple

layers using any one of Mo, Ti, Cu, AlNd, Al and Cr, or an alloy thereof, but the present disclosure is not limited thereto.

[0034] The active layer 104 overlaps the gate electrode 106 via the gate insulation film 112 interposed therebetween, to form a channel between the source and drain electrodes 108 and 110. This active layer 104 is formed using at least one of an amorphous semiconductor material, a polycrystalline semiconductor material and an oxide semiconductor material.

[0035] A buffer film 114 and a light-shielding layer 102 are formed between the active layer 104 and the substrate 101. The light-shielding layer 102 overlaps the active layer 104 on the substrate 101. Since the light-shielding layer 102 absorbs or reflects light emitted from the outside, it can block exterior light from entering the active layer 104. The light-shielding layer 102 is formed using a non-transparent metal such as Mo, Ti, Al, Cu, Cr, Co, W, Ta or Ni.

[0036] The buffer film 114 is formed as a single or multiple layer structure using silicon oxide or silicon nitride on the substrate 101, which may be made of glass or a plastic resin such as polyimide (PI). The buffer film 114 prevents diffusion of moisture or impurities in the substrate 101 or controls transfer rate of heat upon crystallization, thereby facilitating crystallization of the active layer 104.

[0037] The storage capacitor Cst is formed by a storage lower electrode 152 that is overlapped by a storage upper electrode 154, with the interlayer insulation film 116 disposed between the storage lower and upper electrodes 152, 154. The storage lower electrode 152 is formed on the same layer as the gate electrode 106 using the same material as the gate electrode 106, and the storage upper electrode 154 is formed on the same layer as the drain electrode 110 using the same material as the drain electrode 110. The storage lower electrode 152 is connected to the drain electrode 110 of any one of the switching transistor TS and the driving transistor TD, and the storage upper electrode 154 is connected to the drain electrode 110 of the other of the switching transistor TS and driving transistor TD. Although the switching transistor TS is turned off, the voltage charged in the storage capacitor Cst enables the driving transistor TD to supply a constant current until the data signal of the next frame is supplied, thereby allowing the light emitting element 130 to continuously emit light.

[0038] The light emitting element 130 includes an anode 132 connected to the drain electrode 110 of the driving transistor TD, at least one light emitting stack formed on the anode 132 and a cathode 136 formed on the light emitting stack such that the cathode is connected to the low-voltage VSS supply line. Here, the low-voltage VSS supply line supplies a low-voltage VSS lower than the high-voltage VDD supplied through the high-voltage supply line VDL.

[0039] The anode 132 contacts the drain electrode 110 exposed through the pixel contact hole 120 penetrating the protective film 118 and the planarization layer 128. The anode 132 is formed on the planarization layer 128 such that it is exposed in a light emitting region provided by a bank 138. That is, the bank 138 defines boundaries of the light emitting region. In a case where the anode 132 is applied to a bottom emission type organic light emitting display device, the anode 132 is formed as a transparent conductive layer such as an indium-tin-oxide (ITO) or indium-zinc-oxide (IZO) layer.

[0040] The light emitting stack **134** is formed by stacking a hole transport layer HTL, an organic light emitting layer EML and an electron transport layer ETL in this order or a reverse order on the anode **132**. In addition, the light emitting stack **134** may include first and second light emitting stacks **134a** and **134b** which face each other with a charge generation layer CGL interposed therebetween. In this case, the organic light emitting layer EML of any one of the first and second light emitting stacks **134a** and **134b** generates blue light and the organic light emitting layer EML of the other of the first and second light emitting stacks **134a** and **134b** generates yellow-green light, thereby combining to generate white light through the first and second light emitting stacks **134a** and **134b**.

[0041] The cathode **136** is formed on upper and side surfaces of the organic light emitting layer **134** and the bank **138** such that the cathode **136** faces the anode **132** with the organic light emitting layer **134** interposed therebetween. In a case where the cathode **136** is applied to a bottom emission type organic light emitting display device, the cathode **136** has a multilayer structure including a transparent conductive film and a non-transparent conductive film having high reflectivity. The transparent conductive film is formed using a material having a high work-function value such as indium-tin-oxide (ITO) or indium-zinc-oxide (IZO), and the non-transparent conductive film is formed as a single layer or multiple layers using any one of Mo, Ti, Cu, AlNd, Al and Cr, or an alloy thereof. For example, the cathode **136** has a structure in which a transparent conductive film, a non-transparent conductive film and a transparent conductive film are sequentially stacked.

[0042] The color filter **160** is disposed on the protective film **118** such that the color filter **160** overlaps the light emitting region provided or defined by the bank **138**. Any one of red R, green G, and blue B color filters is disposed in the light emitting region of each sub-pixel. That is, the red color filter **160** is disposed in the red R sub-pixel, the green color filter **160** is disposed in the green G sub-pixel and the blue color filter **160** is disposed in the blue B sub-pixel. Accordingly, when white light generated in the light emitting stack **130** passes through the color filter **160**, the color filter **160** renders light of the color corresponding to the color filter **160**. Meanwhile, the color filter **160** may extend so as to cover or at least partially cover at least one of the switching and driving film transistors TS and TD.

[0043] As such, when the light emitting stack **134** produces white light, white light generated in the light emitting stack **134** is incident upon the color filter **160**, thus forming a color image. On the other hand, without the color filter **148**, a color image can be formed by producing light of a color corresponding to each sub-pixel SP by each light emitting stack **134**. That is, the light emitting stack **134** of the red sub-pixel SP can produce red light, the light emitting stack **134** of the green sub-pixel SP can produce green light, and the light emitting stack **134** of the blue sub-pixel SP can produce blue light.

[0044] The planarization layer **128** is formed using a transparent organic insulation material such as an acrylic resin on the substrate provided with the color filter **160**. The planarization layer **128** serves as a white color filter in the white sub-pixel region where the color filter **160** is not formed.

[0045] Meanwhile, the present disclosure includes a reflective barrier **140** which surrounds a perimeter of a light

emitting area EA of each sub-pixel, as shown in FIG. 3A, or which surrounds the perimeter of the light emitting area EA and a perimeter of a circuit area CA, as shown in FIG. 3B.

[0046] The reflective barrier **140** includes an insulation layer **142** and a reflective layer **144** disposed on the insulation layer **142**. The reflective barrier **140** may be referred to herein as a "mirror wall," as the reflective barrier **140** may have a mirror-like reflective surface that reflects light. Similarly, the reflective layer **144** may be referred to herein as a "mirror layer." The insulation layer **142** may be referred to herein as an "insulation wall." It should be readily appreciated that the insulation layer **142** or "insulation wall" may include a plurality of walls having a height and that surround a perimeter of one or more of the light emitting area EA and the circuit area CA, as described herein.

[0047] The insulation wall **142** overlaps a plurality of signal lines which cross each other to provide respective sub-pixel areas and is disposed between the light emitting area EA and the circuit area CA of each sub-pixel. For example, as shown in FIGS. 3A and 3B, the mirror wall **140** and the insulation wall **142** may overlap a data line DL disposed along a first direction (e.g., in a vertical direction, as shown) and therefore faces the left side of each of the light emitting area EA and the circuit area CA, as shown. The insulation wall **142** overlaps a high-voltage supply line VDL parallel to the data line DL and therefore faces the right side of each of the light emitting area EA and the circuit area CA, as shown. The insulation wall **142** overlaps a scan line SL in a second direction crossing the first direction (e.g., in a horizontal direction, as shown) and therefore faces the upper side of the light emitting area EA and the lower side of the circuit area CA, and the insulation wall **142** may be disposed between the light emitting area EA and the circuit area CA and therefore faces the lower side of the light emitting area EA and the upper side of the circuit area CA. Accordingly, the insulation wall **142** surrounds the perimeter of the light emitting area EA of each sub-pixel, as shown in FIG. 3A, and the insulation wall **142** may further surround the perimeter of the circuit area CA of each sub-pixel, as shown in FIG. 3B.

[0048] The reflective barrier or mirror wall **140**, including the insulation wall **142** and the reflective layer or mirror layer **144**, is described herein as surrounding a perimeter of one or both of the light emitting area EA and the circuit area CA of the sub-pixels. It should be readily appreciated that the mirror wall **140** may surround a perimeter of one or both of the light emitting area EA and the circuit area CA without surrounding, for example, a lower or upper portion of the light emitting area EA and the circuit area CA. Further, the term surrounds a perimeter is not intended to impart any height or width limitations, and is sufficiently broad to cover embodiments where the mirror wall **140** has a height that is less than, equal to, or greater than a height of portions of the light emitting area EA and the circuit area CA that form the perimeters.

[0049] The insulation wall **142** is formed on the protective film **118**, and may be formed on the same plane as the planarization layer **128**, using the same material as the planarization layer **128**. In this case, the side surface of the insulation wall **142** forms an acute or right angle with the upper surface of the protective film **118**.

[0050] The mirror layer **144** is formed on the side surfaces of the insulation wall **142**. That is, since the side surface of the insulation wall **142** overlapping the drain electrode **110**

of the driving transistor overlaps the mirror layer 144 via the anode 132, as shown in FIG. 2, the mirror layer 144 is connected to the anode 132. In addition, since the side surface of the insulation wall 142 which overlaps the signal line including the data line DL, the high-voltage supply line VDL and the scan line SL overlaps the mirror layer 144 via the transparent layer 146, as shown in FIG. 4, the mirror layer 144 contacts the transparent layer 146 which is in a floating state. In particular, the mirror layer 144 disposed on the signal line including the data line DL, the high-voltage supply line VDL and the scan line SL covers both side surfaces and the upper surface of the insulation wall 142, as shown in FIG. 4. In addition, in one or more embodiments, the mirror layer 144 disposed on the signal line covers a part of the upper surface and the side surface of the insulation wall 142 while not overlapping the upper surface of each signal line, as shown in FIGS. 5A and 5B. That is, the mirror layer 144 may extend over only a portion of the upper surface of the insulation wall 142, and a portion of the insulation wall 142 that is not covered by the mirror layer 144 may correspond with the signal line which is formed under the insulation wall 142, as shown in FIGS. 5A and 5B.

[0051] The mirror layer 144 may be formed of any reflective material that reflects light. The mirror layer 144 may be formed using the same material as the cathode 136, which may have reflectivity, or may be formed of an insulation, semiconductor or metal material having reflectivity. For example, the mirror layer 144 may be formed as a single layer or multiple layers using any one of molybdenum (Mo), aluminum (Al), chromium (Cr), gold (Au), titanium (Ti), nickel (Ni), neodymium (Nd), copper (Cu) and APC (Ag; Pb;Cu), or an alloy thereof.

[0052] The mirror layer 144 has reflectivity and therefore changes a passage of light total-reflected through the cathode 136, thus reducing light loss due to total reflection. In addition, the mirror layer 144 reflects light, which travels toward the outside of the light emitting area EA, that is, toward the non-light emitting area, to the light emitting area EA, thereby improving optical efficiency of light emitted through the light emitting area EA of the substrate 101. In particular, the upper surface of the mirror layer 144 disposed on the insulation wall 142 is disposed in a higher plane, e.g., relative to a surface of the substrate 101, than the lower surface of the light emitting stack 134 contacting the anode 132. Accordingly, light which is produced from the light emitting stack 134 and travels in a direction parallel or nearly parallel to the length direction of the light emitting stack 136 (that is, a direction perpendicular to the thickness direction of the light emitting stack 136) is reflected by the mirror layer 144 and is redirected to the light emitting area EA, thereby improving optical efficiency. Furthermore, the mirror layer 144 on the insulation wall 142 disposed between the light emitting area EA and the circuit area CA reflects light, which travels toward the switching and driving transistors TS and TD, to the light emitting area EA, thereby preventing deterioration in reliability of the switching and driving transistors TS and TD.

[0053] Meanwhile, the transparent layer 146 is disposed between the mirror layer 144 and the insulation wall 142. The transparent layer 146 is formed by the same mask process as the anode 132 and the mirror layer 144. Accordingly, both ends of the transparent layer 146 correspond to both ends of the mirror layer 144, and the transparent layer 146 is formed on the same plane as the anode 132 using the

same material. As shown in FIG. 4, the mirror layer 144 may cover the upper and side surfaces of the insulation wall 142, or as shown in FIGS. 5A and 5B, the mirror layer 144 may cover a part of the upper surface and the side surface of the insulation wall 142, while not overlapping the upper surface of each signal line.

[0054] As such, the present disclosure can prevent total reflection of light produced in the light emitting stack 134 and thus improve optical efficiency because the mirror layer 144 formed on the insulation wall 142 changes a route of the light produced in the light emitting stack 134. In addition, the present disclosure can improve optical efficiency because the mirror layer 144 formed on the insulation wall 142 collects light travelling toward the non-light emitting area to the light emitting area. Furthermore, the present disclosure can prevent deterioration in reliability of the switching and driving transistors TS and TD because the mirror layer 144 formed on the insulation wall 142 blocks light which is produced in the light emitting element 130 from traveling toward the switching and driving transistors TS and TD.

[0055] FIGS. 6A to 6I are sectional views illustrating a method of manufacturing the organic light emitting display device shown in FIG. 4. Meanwhile, the method of manufacturing the organic light emitting display device shown in FIGS. 6A to 6I will be described in conjunction with the organic light emitting display device shown in FIG. 4 as well as the organic light emitting display device shown in FIG. 2.

[0056] Referring to FIG. 6A, a light-shielding layer 102, a switching transistor TS, a driving transistor TD, a storage capacitor Cst, a high-voltage supply line VDL and a data line DL are formed on a substrate 101 by five or fewer mask processes.

[0057] More specifically, the light-shielding layer 102 is formed on the substrate 101 by a first mask process. Here, the light-shielding layer 102 is formed as a single layer using a metal material such as Mo, Ti, Cu, AlNd, Al or Cr, or an alloy thereof, or as multiple layers using the same. A buffer film 114 is formed on the substrate 101 provided with the light-shielding layer 102, and an active layer 104 is formed on the buffer film 114 by a second mask process. Then, at the same time, by a third mask process, a gate insulation pattern 112 is formed on the buffer film 114 provided with the active layer 104, and a scan line SL, a gate electrode 106 and a storage lower electrode 152 are formed on the gate insulation pattern 112. Then, an interlayer insulation film 116 having source and drain contact holes 124S and 124D is formed on the substrate 101 provided with the scan line SL, the gate electrode 106 and the storage lower electrode 152 by a fourth mask process. Then, a data line DL, a high-voltage supply line VDL, a source electrode 108, a drain electrode 110 and a storage upper electrode 154 are formed on the substrate 101 provided with the interlayer insulation film 116 by a fifth mask process.

[0058] Then, an inorganic insulation material such as SiO_x or SiN_x is deposited over the entire surface of the interlayer insulation film 116 provided with the data line DL, the high-voltage VDL supply line, the source electrode 108, the drain electrode 110 and the storage upper electrode 154 to form a protective film 118 as shown in FIG. 6B. Then, the substrate 101 provided with the protective film 118 is coated with a colored resin and the colored resin is then patterned by a sixth mask process to form a color filter 160.

[0059] An organic film such as a photoacrylic resin is coated over the entire surface of the substrate **101** provided with color filter **160** and is then patterned by a seventh mask process, to form an insulation wall **142**, a planarization layer **128** and a pixel contact hole **120**, as shown in FIG. 6C.

[0060] Then, first and second conductive layers **172** and **174** and a photoresist are sequentially deposited over the entire surface of the substrate **101** provided with the insulation wall **142**, the planarization layer **128** and the pixel contact hole **120**, as shown in FIG. 6D. Then, an eighth mask **180** having a light-shielding part **186** and a semi-transmission part **184** on a mask substrate **182** is arranged on the substrate **101** provided with the photoresist. The photoresist is patterned by a photolithography process using this eighth mask to form a multi-step photoresist pattern **170**. In this case, the photoresist pattern **170** is formed to have a first thickness in a region where the photoresist pattern **170** overlaps the semi-transmission part **184** and to have a second thickness greater than the first thickness in a region where the photoresist pattern **170** overlaps the light-shielding part **186**.

[0061] Then, the first and second conductive layers **172** and **174** are patterned by an etching process using the multi-step photoresist pattern **170** as a mask, to form a transparent layer **146** including the first conductive layer **172**, a mirror layer **144** including the second conductive layer **174**, and an anode **132** including the first and second conductive layers **172** and **174**, as shown in FIG. 6E.

[0062] Then, the multi-step photoresist pattern **170** is ashed, so that the thickness of the photoresist pattern **170** having a second thickness on the mirror layer **144** is reduced and the photoresist pattern **170** having the first thickness on the anode **132** is removed, to expose the second conductive layer **174** of the anode **132**, as shown in FIG. 6F. The exposed second conductive layer **174** is removed by an etching process using the ashed photoresist pattern **170** as a mask to form the anode **132** as the first conductive layer **172**, as shown in FIG. 6G. Then, photoresist pattern **170** remaining on the mirror wall **140** is removed by a stripping process. The upper surface of the mirror layer **144** is thus formed at a higher level above the surface of the substrate **101** than the upper surface of the anode **132** in the light emitting area.

[0063] Then, a photosensitive organic film is deposited over the entire surface of the substrate **101** provided with the transparent layer **146**, the mirror layer **144** and the anode **132**, and the photosensitive organic film is patterned by a photolithography process using a ninth mask to form a bank **138**, as shown in FIG. 6H. A light emitting stack **134** rendering white light and a cathode **136** are sequentially formed on the substrate **101** provided with the bank **138** by a deposition process using a shadow mask, as shown in FIG. 6I.

[0064] As such, the method of manufacturing the organic light emitting display device according to the present disclosure can prevent an increase in the number of processes because the insulation wall **142** is formed by the same mask process as the planarization layer **128**, and the mirror layer **144** and the transparent layer **146** are formed by the same mask process as the anode **132**.

[0065] According to the present disclosure, the mirror wall including the insulation wall and the mirror layer disposed on the insulation wall surrounds the light emitting area. Accordingly, the present disclosure can prevent total reflection of light produced in the light emitting stack and thus

improve optical efficiency because the mirror layer changes a route of the light produced in the light emitting stack. In addition, the present disclosure can improve optical efficiency because the mirror layer formed on the insulation wall reflects light travelling toward the non-light emitting area to be redirected toward the light emitting area. Furthermore, the present disclosure can prevent deterioration in reliability of the switching and driving transistors because the mirror layer formed on the insulation wall blocks light which is produced in the light emitting element from travelling toward the switching and driving transistors.

[0066] In addition, it will be apparent to those skilled in the art that various modifications and variations can be made in the present disclosure without departing from the spirit or scope of the disclosure. Accordingly, the embodiments described in the present disclosure are not limited to the present disclosure. Thus, it is intended that the present disclosure covers the modifications and variations of this disclosure provided they come within the scope of the appended claims and their equivalents.

[0067] The various embodiments described above can be combined to provide further embodiments. These and other changes can be made to the embodiments in light of the above-detailed description. In general, in the following claims, the terms used should not be construed to limit the claims to the specific embodiments disclosed in the specification and the claims, but should be construed to include all possible embodiments along with the full scope of equivalents to which such claims are entitled. Accordingly, the claims are not limited by the disclosure.

What is claimed is:

1. An organic light emitting display device comprising:
 - a substrate;
 - a plurality of sub-pixels on the substrate, each of the sub-pixels including:
 - a light emitting element disposed in a light emitting area; and
 - a pixel circuit disposed in a circuit area, the pixel circuit configured to operate the light emitting element; and
 - a reflective barrier disposed overlying the substrate and surrounding a perimeter of the light emitting area of each sub-pixel.
2. The organic light emitting display device according to claim 1, wherein the reflective barrier comprises:
 - an insulation layer surrounding the perimeter of the light emitting area of each sub-pixel; and
 - a reflective layer disposed on the insulation layer.
3. The organic light emitting display device according to claim 2, further comprising:
 - a transparent layer disposed between the insulation layer and the reflective layer.
4. The organic light emitting display device according to claim 3, further comprising:
 - a color filter disposed between the substrate and the light emitting element; and
 - a planarization layer on the color filter,
 wherein the insulation layer and the planarization layer are formed of a same material and are disposed on a same plane, and
 - the transparent layer and an anode of the light emitting element are formed of a same material and are disposed on a same plane.
5. The organic light emitting display device according to claim 1, wherein the reflective barrier comprises:

- an insulation layer surrounding the perimeter of the light emitting area and surrounding a perimeter of the circuit area of each sub-pixel; and
 a reflective layer disposed on the insulation layer.
- 6.** The organic light emitting display device according to claim **5**, further comprising:
 a transparent layer disposed between the insulation layer and the reflective layer.
- 7.** The organic light emitting display device according to claim **5**, wherein the insulating layer includes portions that extend between the light emitting area and the circuit area of each sub-pixel.
- 8.** The organic light emitting display device according to claim **5**, further comprising:
 a color filter disposed between the substrate and the light emitting element; and
 a planarization layer on the color filter,
 wherein the insulation layer and the planarization layer are formed of a same material and are disposed on a same plane, and
 the transparent layer and an anode of the light emitting element are formed of a same material and are disposed on a same plane.
- 9.** The organic light emitting display device according to claim **2**, wherein the reflective layer is disposed on a side surface of the reflective barrier facing the light emitting area.
- 10.** The organic light emitting display device according to claim **1**, wherein the reflective layer is formed using a same material as a cathode of the light emitting element.
- 11.** The organic light emitting display device according to claim **1**, wherein the reflective layer is formed as a single layer or multiple layers including at least one of molybdenum (Mo), aluminum (Al), chromium (Cr), gold (Au), titanium (Ti), nickel (Ni), neodymium (Nd), copper (Cu) and APC (Ag;Pb;Cu), or an alloy thereof.
- 12.** The organic light emitting display device according to claim **2**, wherein the pixel circuit comprises:
 a driving transistor connected to the light emitting element; and
 a switching transistor connected to the driving transistor, wherein the reflective barrier is disposed between the light emitting area and the circuit area.
- 13.** The organic light emitting display device according to claim **12**, further comprising:
 a scan line connected to a gate electrode of the switching transistor;
 a data line connected to a source electrode of the switching transistor; and
 a high-voltage supply line connected to a source electrode of the driving transistor,
 wherein the reflective barrier overlaps with the scan line, the data line and the high-voltage supply line.
- 14.** The organic light emitting display device according to claim **12**, wherein the light emitting element comprises:
 an anode connected to the switching transistor;
 a cathode facing the anode; and
 a light emitting stack disposed between the anode and the cathode,
 wherein an upper surface of the reflective layer disposed on the insulation layer is disposed on a higher plane relative to the substrate than a lower surface of the light emitting stack contacting the anode.
- 15.** The organic light emitting display device according to claim **14**, wherein the reflective layer and the cathode reflect light produced in the light emitting stack toward the substrate.
- 16.** A method of manufacturing an organic light emitting display device comprising:
 forming a pixel circuit in a pixel area of a sub-pixel on a substrate;
 forming a light emitting element in a light emitting area of the sub-pixel; and
 forming a reflective barrier on the substrate, the reflective barrier surrounding a perimeter of the light emitting area.
- 17.** The method of claim **17**, wherein forming the reflective barrier includes:
 forming an insulation layer surrounding the perimeter of the light emitting area; and
 forming a reflective layer on at least a side surface of the insulating layer facing the light emitting area.
- 18.** The method of claim **17**, wherein forming the reflective layer includes forming the reflective layer to have an upper surface disposed at a height from a surface of the substrate that is greater than a height of an anode of the light emitting element from the surface of the substrate.
- 19.** The method of claim **16**, wherein forming the pixel circuit includes:
 forming a driving transistor connected to the light emitting element; and
 forming a switching transistor connected to the driving transistor.
- 20.** The method of claim **19** wherein forming the reflective barrier includes:
 forming at least a portion of the reflective barrier between the light emitting area and the pixel circuit area.

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摘要(译)

公开了一种有机发光显示装置及其制造方法，该有机发光显示装置用于提高光学效率并防止薄膜晶体管的可靠性劣化。有机发光显示装置包括镜壁，该镜壁设置在基板上，使得镜壁围绕设置有发光元件的每个子像素的发光区域，从而防止在发光中产生的光的全反射通过将朝向非发光区域行进的光反射以引导到发光区域，提高光学效率。

